

LM380 2.5W Audio Power Amplifier

 Check for Samples: [LM380](#)

FEATURES

- **Wide Supply Voltage Range: 10V-22V**
- **Low Quiescent Power Drain: 0.13W ($V_S = 18V$)**
- **Voltage Gain Fixed at 50**
- **High Peak Current Capability: 1.3A**
- **Input Referenced to GND**
- **High Input Impedance: 150k Ω**
- **Low Distortion**
- **Quiescent Output Voltage is at One-Half of the Supply Voltage**
- **Standard Dual-In-Line Package**

DESCRIPTION

The LM380 is a power audio amplifier for consumer applications. In order to hold system cost to a minimum, gain is internally fixed at 34 dB. A unique input stage allows ground referenced input signals. The output automatically self-centers to one-half the supply voltage.

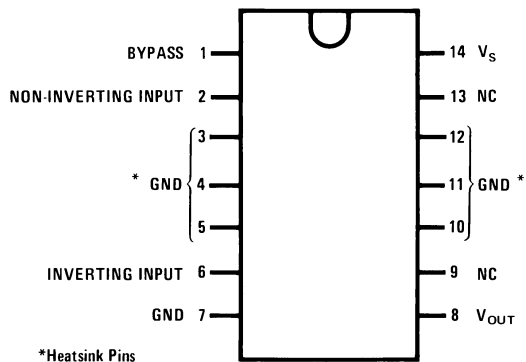
The output is short circuit proof with internal thermal limiting. The package outline is standard dual-in-line. The LM380N uses a copper lead frame. The center three pins on either side comprise a heat sink. This makes the device easy to use in standard PC layouts.

Uses include simple phonograph amplifiers, intercoms, line drivers, teaching machine outputs, alarms, ultrasonic drivers, TV sound systems, AM-FM radio, small servo drivers, power converters, etc.

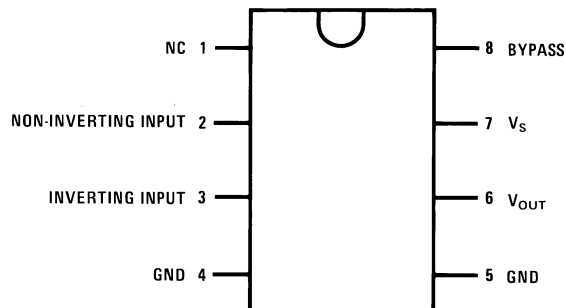
A selected part for more power on higher supply voltages is available as the LM384. For more information see [SNAA086](#).

Connection Diagrams

(Dual-In-Line Packages, Top View)



**Figure 1. 14-Pin PDIP
See NFF0014A Package**



**Figure 2. 8-Pin PDIP
See P Package**



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Block and Schematic Diagrams

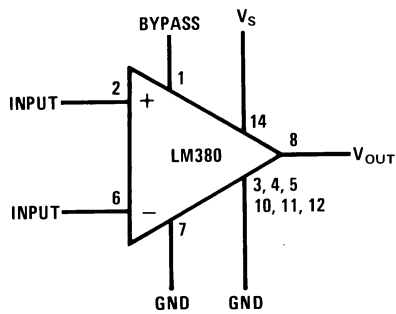


Figure 3. 14-Pin PDIP

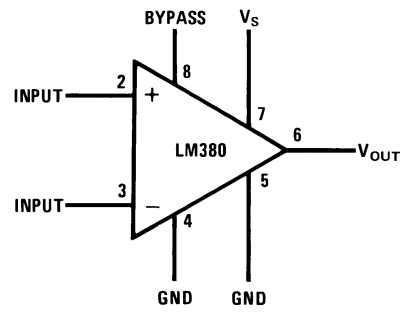


Figure 4. 8-Pin PDIP

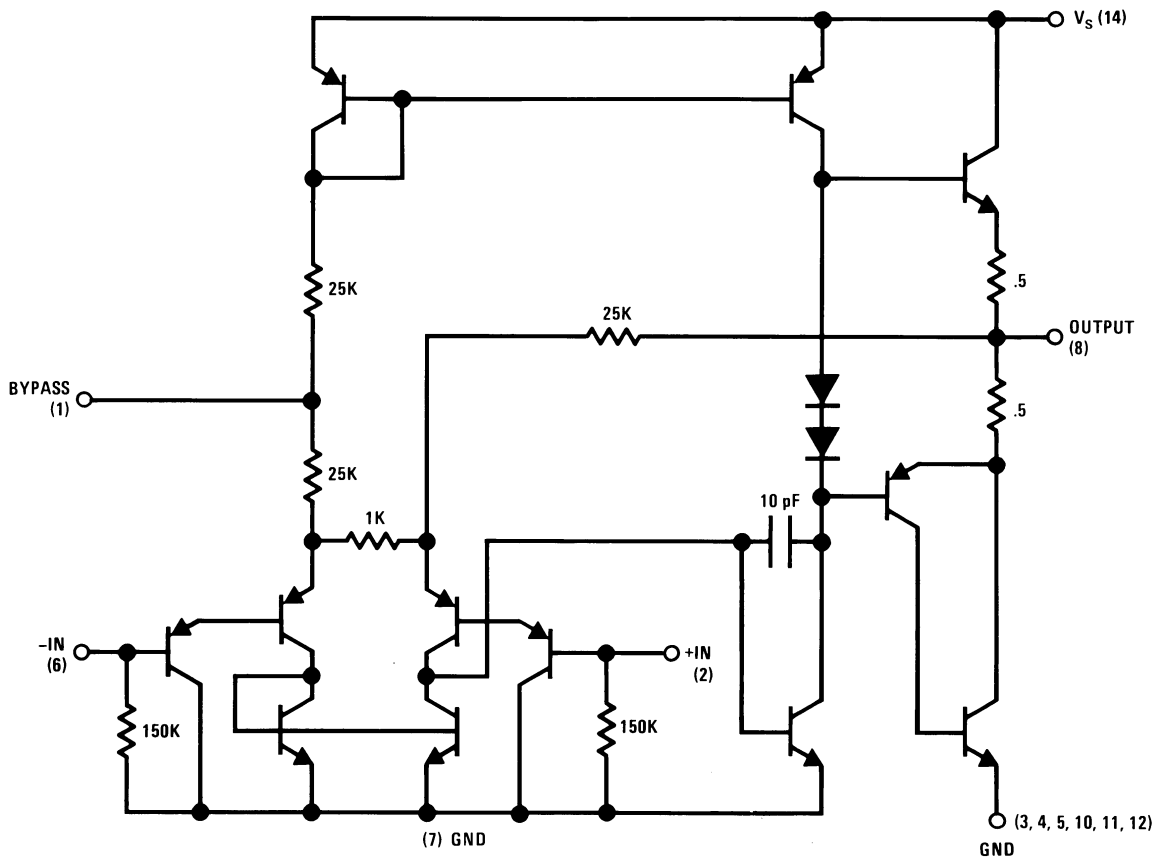


Figure 5.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings⁽¹⁾⁽²⁾

Supply Voltage		22V
Peak Current		1.3A
Package Dissipation	14-Pin PDIP ⁽³⁾	8.3W
	8-Pin PDIP ⁽³⁾	1.67W
Input Voltage		±0.5V
Storage Temperature		–65°C to +150°C
Operating Temperature		0°C to +70°C
Junction Temperature		+150°C
Lead Temperature (Soldering, 10 sec.)		+260°C
ESD rating to be determined		
Thermal Resistance	θ_{JC} (14-Pin PDIP)	30°C/W
	θ_{JC} (8-Pin PDIP)	37°C/W
	θ_{JA} (14-Pin PDIP)	79°C/W
	θ_{JA} (8-Pin PDIP)	107°C/W

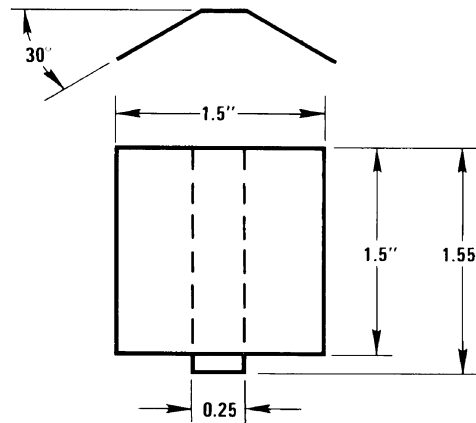
- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/Distributors for availability and specifications.
- (3) The package is to be derated at 15°C/W junction to heat sink pins for 14-pin pkg; 75°C/W for 8-pin.

Electrical Characteristics⁽¹⁾

Symbol	Parameter	Conditions	Min	Typ	Max	Units
$P_{OUT(RMS)}$	Output Power	$R_L = 8\Omega$, THD = 3% ⁽²⁾⁽³⁾	2.5			W
A_V	Gain		40	50	60	V/V
V_{OUT}	Output Voltage Swing	$R_L = 8\Omega$		14		V_{p-p}
Z_{IN}	Input Resistance			150k		Ω
THD	Total Harmonic Distortion	See ⁽³⁾⁽⁴⁾		0.2		%
PSRR	Power Supply Rejection Ratio	See ⁽⁵⁾		38		dB
V_S	Supply Voltage		10		22	V
BW	Bandwidth	$P_{OUT} = 2W$, $R_L = 8\Omega$		100k		Hz
I_Q	Quiescent Supply Current			7	25	mA
V_{OUTQ}	Quiescent Output Voltage		8	9.0	10	V
I_{BIAS}	Bias Current	Inputs Floating		100		nA
I_{SC}	Short Circuit Current			1.3		A

- (1) $V_S = 18V$ and $T_A = 25^\circ C$ unless otherwise specified.
- (2) With device Pins 3, 4, 5, 10, 11, 12 soldered into a 1/16" epoxy glass board with 2 ounce copper foil with a minimum surface of 6 square inches.
- (3) $C_{BYPASS} = 0.47 \mu fd$ on Pin 1.
- (4) The maximum junction temperature of the LM380 is 150°C.
- (5) Rejection ratio referred to the output with $C_{BYPASS} = 5 \mu F$.

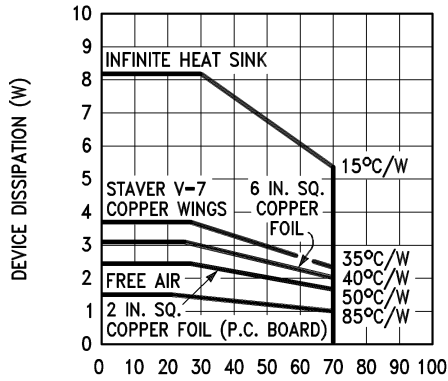
Heat Sink Dimensions



Staver Heat Sink #V-7
Staver Company
41 Saxon Ave.
P.O. Drawer H
Bayshore, NY 11706
Tel: (516) 666-8000
Copper Wings
2 Required
Soldered to
Pins 3, 4, 5,
10, 11, 12
Thickness 0.04
Inches

Typical Performance Characteristics

Maximum Device Dissipation vs Ambient Temperature



T_A – AMBIENT TEMPERATURE ($^{\circ}\text{C}$)
 Note: 2 oz. copper foil, single-sided PC board.

Figure 6.

Device Dissipation vs Output Power—4 Ω Load

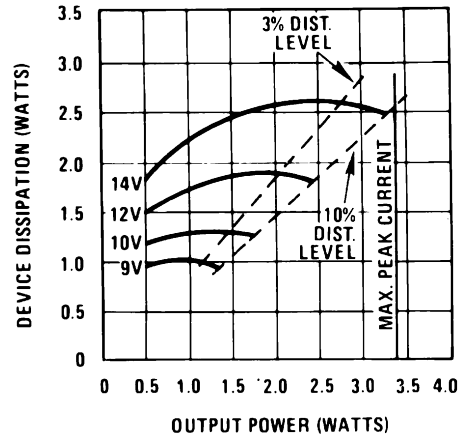


Figure 7.

Device Dissipation vs Output Power—8 Ω Load

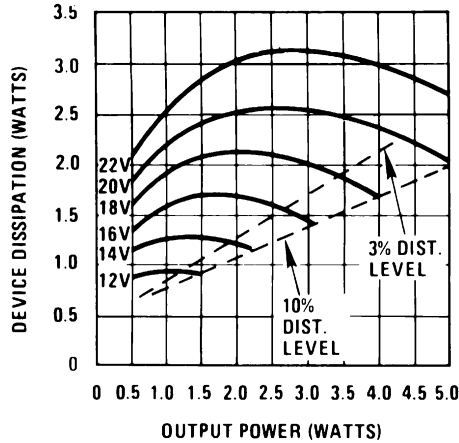


Figure 8.

Device Dissipation vs Output Power—16 Ω Load

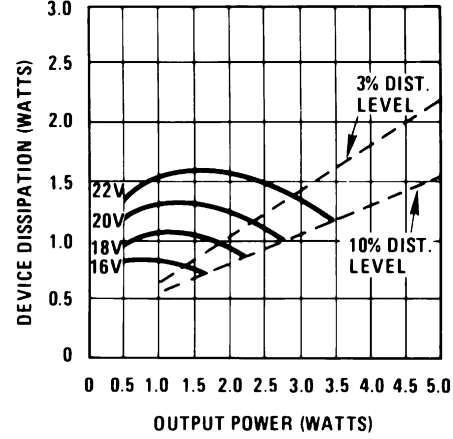


Figure 9.

Power Supply Current vs Supply Voltage

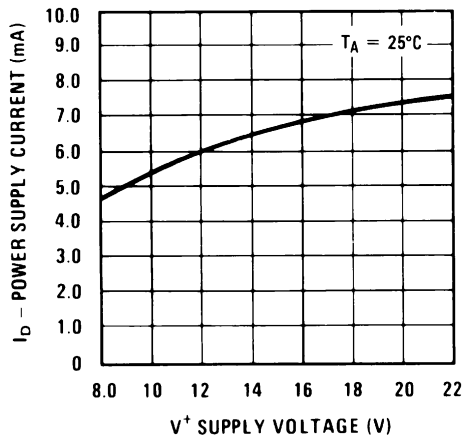


Figure 10.

Total Harmonic Distortion vs Frequency

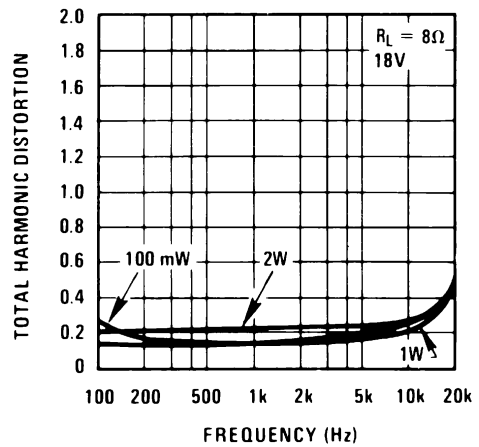


Figure 11.

Typical Performance Characteristics (continued)

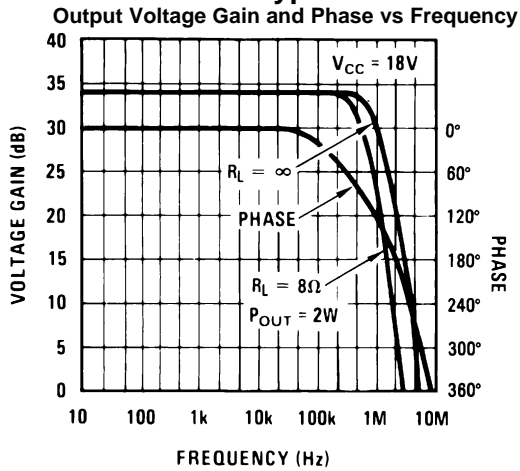


Figure 12.

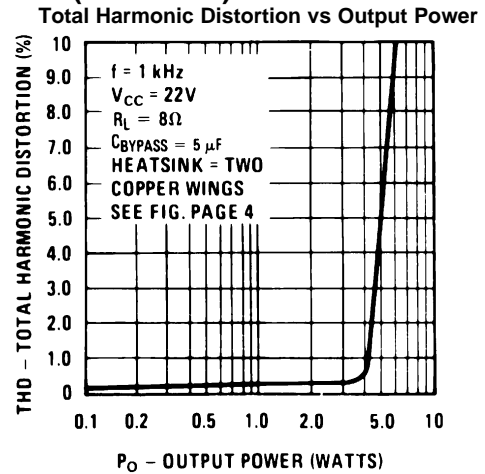


Figure 13.

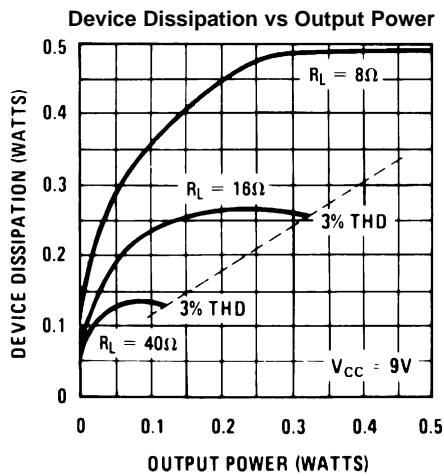


Figure 14.

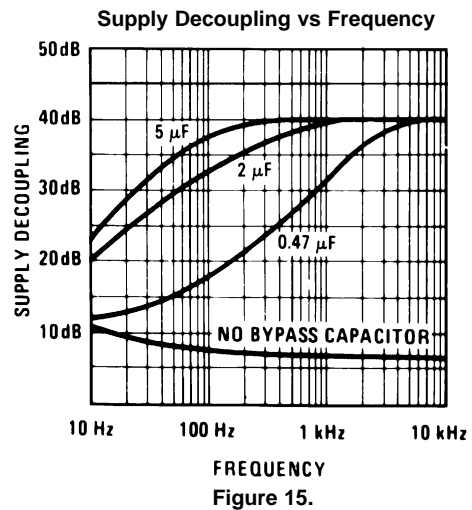


Figure 15.

Typical Applications

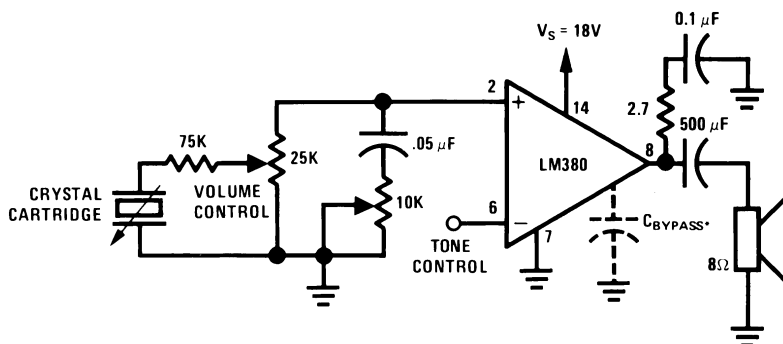


Figure 16. Phono Amplifier

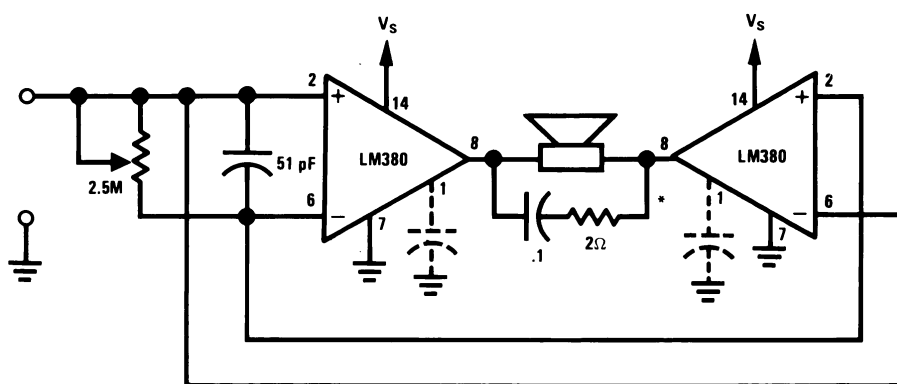
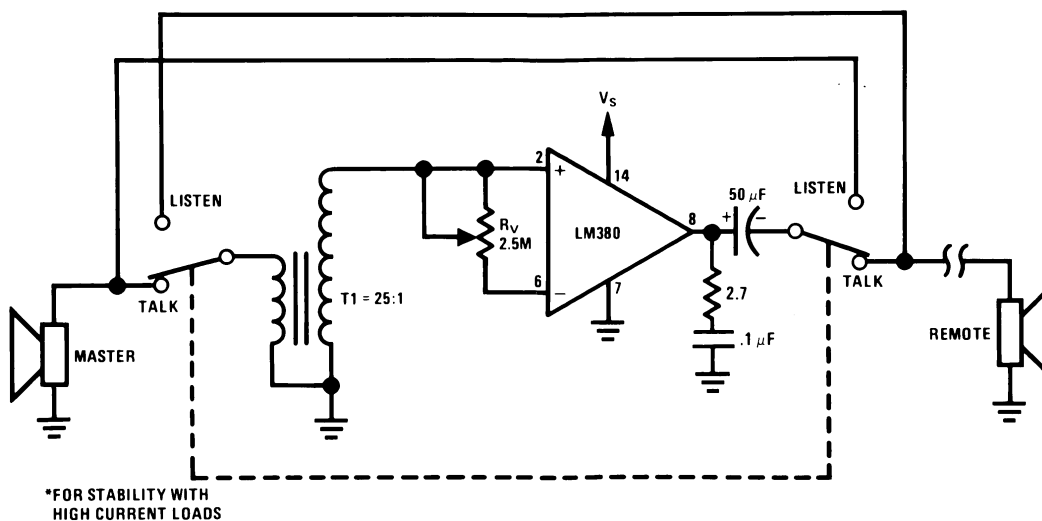


Figure 17. Bridge Amplifier



*FOR STABILITY WITH HIGH CURRENT LOADS

Figure 18. Intercom

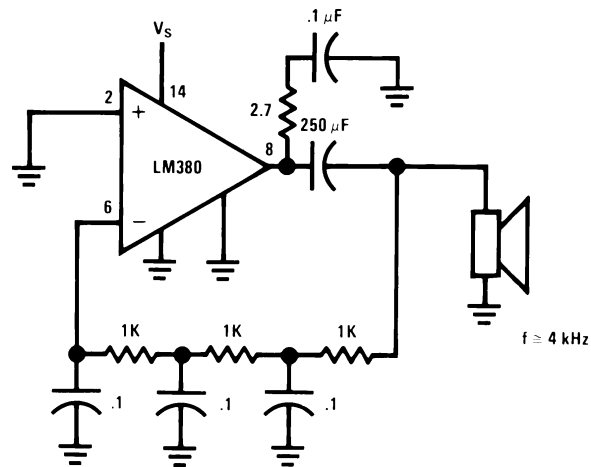


Figure 19. Phase Shift Oscillator

REVISION HISTORY

Changes from Revision B (April 2013) to Revision C	Page
<hr/> <ul style="list-style-type: none">• Changed layout of National Data Sheet to TI format	<hr/> 8

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM380N-8/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM 380N-8	Samples
LM380N/NOPB	ACTIVE	PDIP	NFF	14	25	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM380N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSELETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

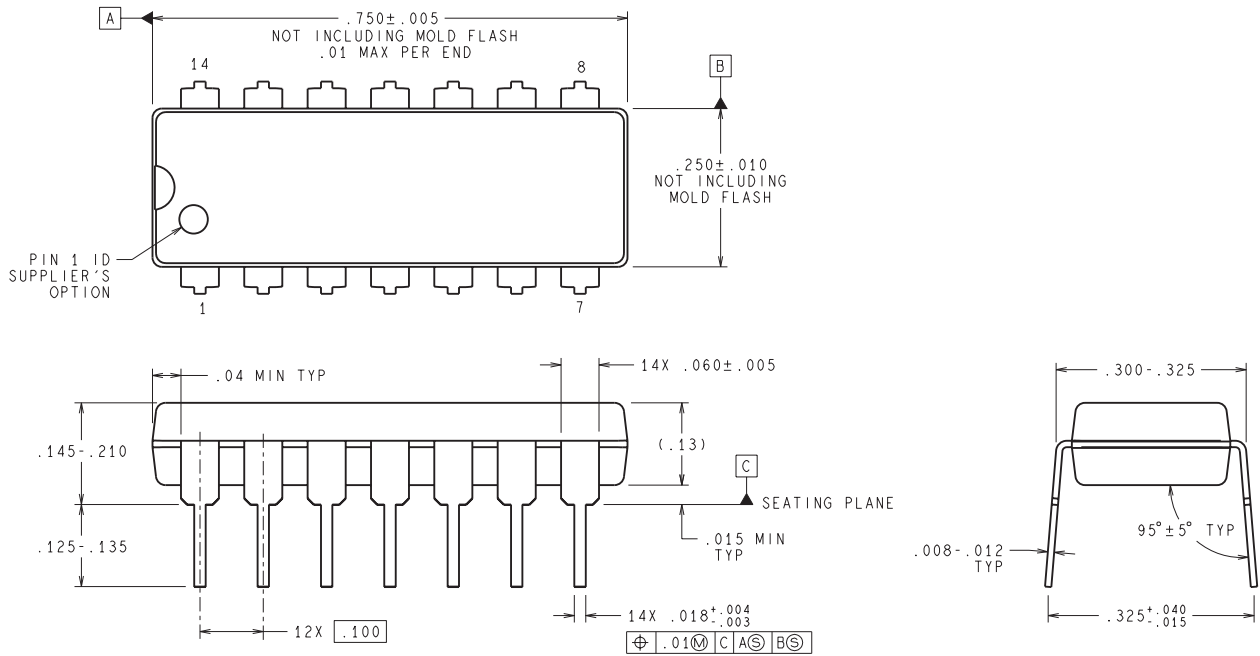
(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

NFF0014A



DIMENSIONS ARE IN INCHES
DIMENSIONS IN () FOR REFERENCE ONLY

N14A (Rev G)

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com